



3D Packaging & Integration Taiwan TC Chapter

Meeting Summary and Minutes

Taiwan Summer Standards Meeting 2019

Tuesday, June 11, 2019, 14:30 – 16:00

11F-2, No. 1, Taiyuan 1st Street, Zhubei City, Hsinchu County, Taiwan

TC Chapter Announcements

Next TC Chapter Meeting

TBD, 2019

11F-2, No. 1, Taiyuan 1st Street, Zhubei City, Hsinchu County, Taiwan

Table 1 Meeting Attendees

Co-Chairs: Roger Hwang (ASE)

SEMI Staff: Dean Chang / Tiffany Huang

<i>Company</i>	<i>Last</i>	<i>First</i>	<i>Company</i>	<i>Last</i>	<i>First</i>
ITRI	Chen	Shang-Chun	KYEC	Hsu	Bernard
ITRI	Chang	Hsiang- Hung	KYEC	Chen	Wendy
ITRI	Ou Yang	Tsung Yu			

Table 2 Leadership Changes

<i>WG/TF/SC/TC Name</i>	<i>Previous Leader</i>	<i>New Leader</i>
None		

Table 3 Committee Structure Changes

<i>Previous WG/TF/SC Name</i>	<i>New WG/TF/SC Name or Status Change</i>
None	

Table 4 Ballot Results

<i>Document #</i>	<i>Document Title</i>	<i>Committee Action</i>
None		

#1 **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

#2 **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 5 Activities Approved by the GCS between meetings of the TC Chapter

<i>#</i>	<i>Type</i>	<i>SC/TF/WG</i>	<i>Details</i>
None			

Table 6 Authorized Activities

Listing of all revised or new SNARF(s) approved by the Originating TC Chapter.

#	Type	SC/TF/WG	Details
None			

#1 SNARFs and TFOFs are available for review on the SEMI Web site at:

<http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF>

Table 7 Authorized Ballots

#	When	TF	Details
None			

Table 8 SNARF(s) Granted a One-Year Extension

#	TF	Title	Expiration Date
None			

Table 9 SNARF(s) Abolished

#	TF	Title
None		

Table 10 Standard(s) to receive Inactive Status

Standard Designation	Title
None	

Table 11 New Action Items

Item #	Assigned to	Details
1	Shang-Chun Chen	Will still following the Device ID issue.
2	Mike Chang	Will still discuss CMP issue with Arthur Chen.
3	Dean Chang	Will share the Standards Watch link to members.

Table 12 Previous Meeting Action Items

Item #	Assigned to	Details
1	Shang-Chun Chen	Stop to draft SNARF for “New Standard, Guideline for Chip ID registering and tracing”.
2	Mike Chang	Middle End Process Task Force will discuss new issue.

1 Welcome, Reminders, and Introductions

Committee Co-Chair Roger Hwang (ASE) called the meeting to order at 14:30. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance reviewed. Attendees introduced themselves.

Attachment: [Meeting Reminder 2019](#)

2 Review of Previous Meeting Minutes

The TC Chapter reviewed the minutes of the previous meeting.

Motion: Approve previous meeting minute
By / 2nd: Wendy Chen(ITRI) / Hsiang- Hung Chang (ITRI)
Discussion: After review, all TC members agreed to approve it
Vote: 5-0 in favor, Motion passed

Attachment: [20190326_3D Meeting Minutes](#)

3 Liaison Reports

3.1 3D Packaging & Integration North America TC Chapter

Dean Chang (SEMI) reported for the 3D Packaging & Integration North America TC Chapter. Of note:

- Next TC Meeting will be held on July 11, 2019
- Leadership Changes: 3DP&I NA TC Chapter-Richard Allen (NIST) was Stepped down.
- Ballots results
 - Cycle 1-19
 - Doc (6075A, 6332A) passed as balloted.
 - Doc 6175A was failed.

Attachment: [NA 3DP&I Liaison Report Apr2019 v4](#)

3.2 3D Packaging & Integration Japan TC Chapter

Dean Chang (SEMI) reported for the 3D Packaging & Integration Japan TC Chapter. Of note:

- Next TC Meeting will be held on October 11, 2019
- Panel Level Packaging (PLP) Glass Carrier Task Force is newly formed.
 - Mark Takahashi (Namics Corporation) is new leader.
- Ballot Results
 - Passed with editorial change: Doc6497 Line Item Revision to SEMI G95-0314 with non-conforming title change to "Specification for Mechanical Features of 450 mm Load Port for Tape Frame Cassettes in The Backend Process"
 - Passed as balloted: Doc6498 Reapproval of SEMI G96-1014 Test Method for Measurement of Chip (Die) Strength by Mean of Cantilever Bending

Attachment: [20190607_3DP&I-Japan Liaison v1.0](#)

3.3 SEMI Staff Report

Dean Chang (SEMI) gave the SEMI Staff Report. Of note:

- SEMI Global 2019 Calendar of Events
- 2019 Critical Dates for SEMI Standards Ballots
- Introduce the NA 3D P&I TC information, which will be held on July 11 during SEMICON West 2019.
- Share the Standards Watch link to members.



Attachment: 3D P&I TC Meeting Staff Report 20190611

4 Ballot Review

NOTE 1: TC Chapter adjudication on ballots reviewed is detail in the Audits & Review (A&R) Subcommittee Forms for procedural review. The A&R forms are available as attachments to these minutes. The attachment number for each balloted document provided under each ballot review section below.

Doc #	Document Title	TC Chapter Action
None		

5 Subcommittee and Task Force Reports

5.1 Testing Task Force

Shang-Chun Chen (ITRI) reported for the Testing Task Force. This report contained information on:

- Introduce Device ID issue to members.

Attachment: 3D P&I Task Force Report 20190611

5.2 Middle End Process Task Force

Mike Chang (ITRI) reported for the Testing Task Force. This report contained information on:

- Introduce CMP issue to members.

Attachment: 20190611-Cu-oxide hybrid bonding, CMP STD

6 Old Business

6.1 Testing Task Force will stop to draft SNARF for “New Standard, Guideline for Chip ID registering and tracing”.

6.2 Middle End Process Task Force will discuss new issue.

7 New Business

7.1 Shang-Chun Chen will still following the Device ID issue.

7.2 Mike Chang will still discuss CMP issue with Arthur Chen.

7.3 Dean Chang will share the Standards Watch link to members.

8 Next Meeting and Adjournment

The next meeting scheduled for TBD, 2019 at SEMI Taiwan Office. See <http://www.semi.org/standards-events> for the current list of events.

Adjournment was at 16:00.

Respectfully submitted by:

Dean Chang

Senior Executive Consultant



SEMI Taiwan

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Minutes tentatively approved by:

Wendy Chen (KYECC), Co-chair	2019/10/8
Chien-chung Lin (ITRI), Co-chair	2019/10/8

Table 13 Index of Available Attachments#1

<i>Title</i>	<i>Title</i>
1_ Meeting Reminder_2019	3.3_3D P&I TC Meeting Staff Report_20190611
2_ 20190326_3D Meeting Minutes	5.1_3D P&I Task Force Report_20190611
3.1_ NA 3DP&I Liaison Report Apr2019 v4	5.2_20190611-Cu-oxide hybrid bonding, CMP STD
3.2_ 20190607_3DP&I-Japan_Liaison_v1.0	

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact [SEMI Staff Name] at the contact information above.